

SURFACE MOUNT SILICON SCHOTTKY DIODE



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DESCRIPTION:

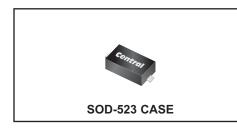
The CENTRAL SEMICONDUCTOR CMOSH-3 is a silicon Schottky diode, epoxy molded in an SOD-523 surface mount package, designed for fast switching applications requiring a low forward voltage drop.

MARKING CODE: 53

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Continuous Forward Current	١ _F	100	mA
Peak Repetitive Forward Current	^I FRM	350	mA
Peak Forward Surge Current, tp=10ms	IFSM	750	mA
Power Dissipation	PD	250	mW
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C
Thermal Resistance	Θ_{JA}	500	°C/W
	unloss othonwise no	(hot	

	CHARACTERISTICS: (T _A =25°C un		e noted) TYP	MAY	UNITO	
SYMBOL	TEST CONDITIONS V _R =25V	MIN	90	MAX 500	UNITS nA	
^I R	IX					
IR	V _R =25V, T _A =100°C		25	100	μA	
BVR	I _R =100μΑ	30			V	
VF	I _F =2.0mA		0.29	0.33	V	
VF	I _F =15mA		0.37	0.45	V	
VF	I _F =100mA		0.51	1.00	V	
CJ	V _R =1.0V, f=1.0MHz		7.0		pF	
t _{rr}	$I_F = I_R = 10 \text{mA}, I_{rr} = 1.0 \text{mA}, R_L = 100 \Omega$			5.0	ns	

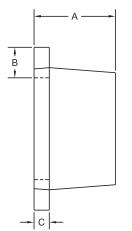




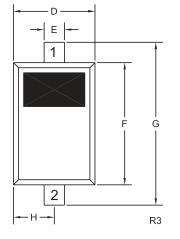


CMOSH-3

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SOD-523 CASE - MECHANICAL OUTLINE



LEAD CODE:	
1) Cathode	
2) Anode	

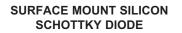
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DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
А	0.020	0.031	0.50	0.80		
В	0.008	0.016	0.20	0.40		
С	0.002	0.008	0.05	0.20		
D	0.028	0.035	0.70	0.90		
E	0.008	0.014	0.20	0.35		
F	0.039	0.055	1.00	1.40		
G	0.055	0.071	1.40	1.80		
Н	0.016		0.40			
SOD-523 (REV: R3)						

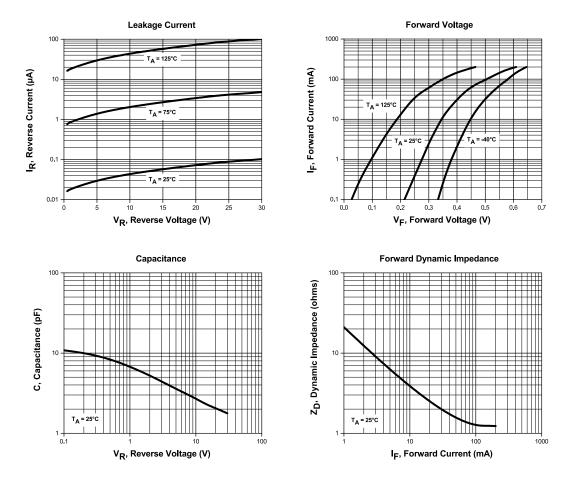
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TYPICAL ELECTRICAL CHARACTERISTICS

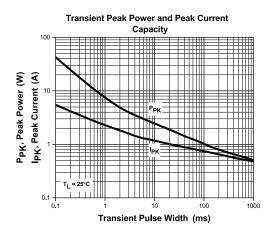
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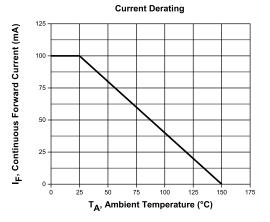


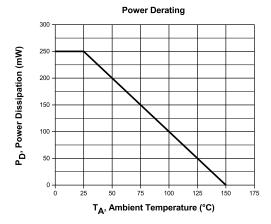
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TYPICAL ELECTRICAL CHARACTERISTICS





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OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

Special wafer diffusions

· Custom product packing

- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

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